



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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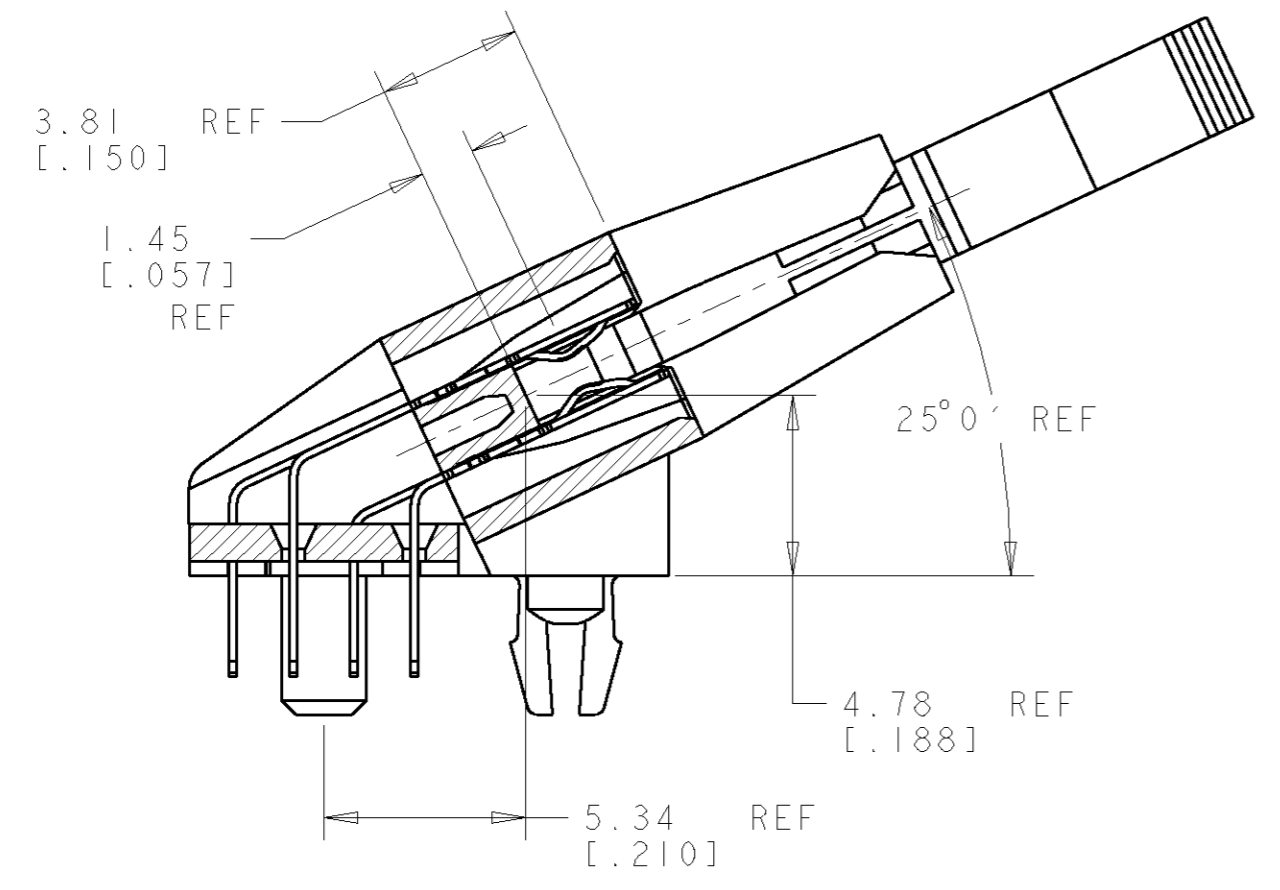
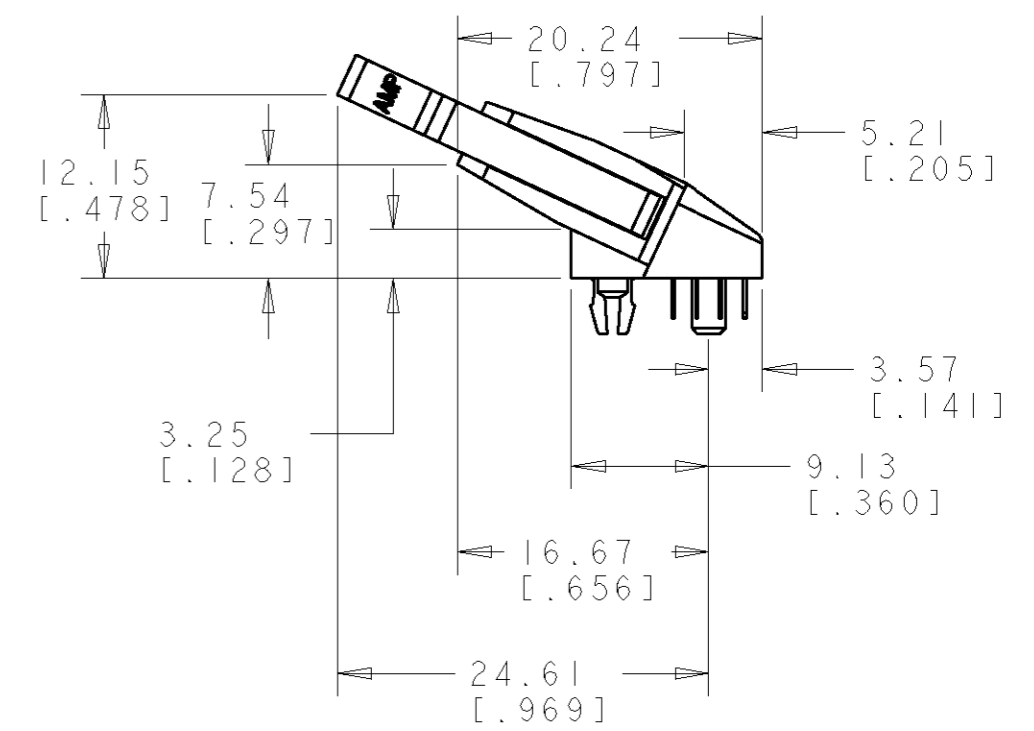
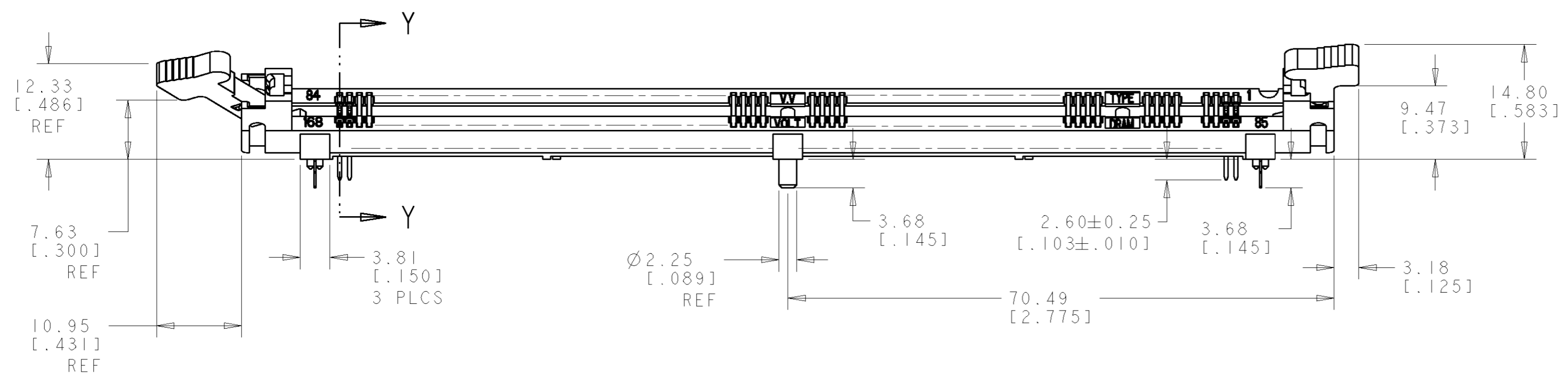
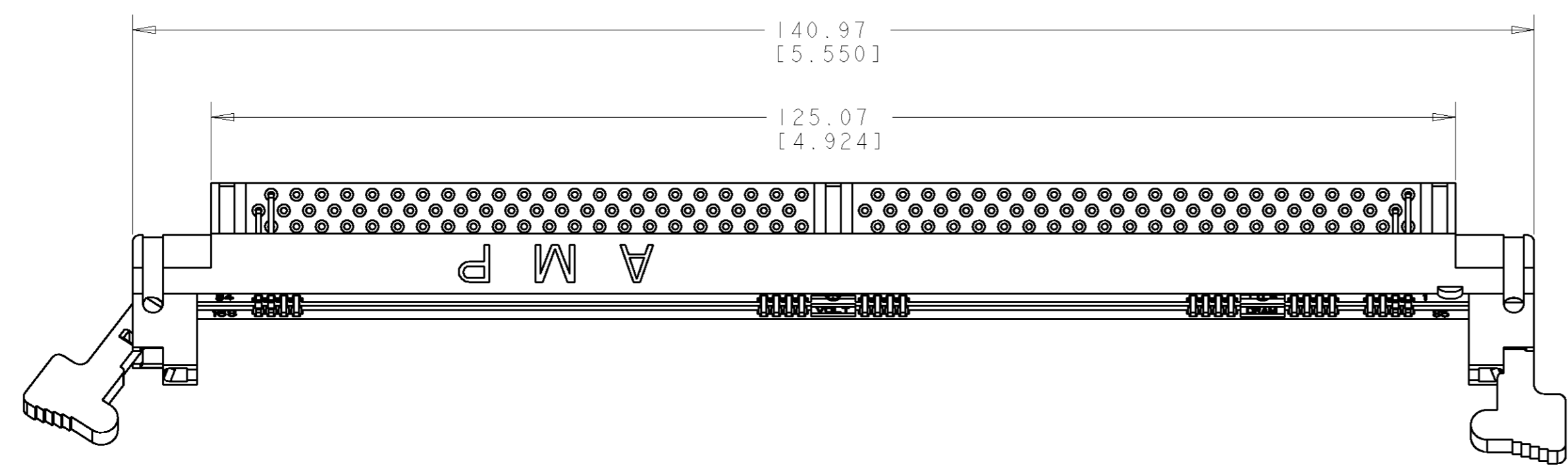
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LOC	DIST	REVISIONS					
GP	0	P	LTR	DESCRIPTION	DATE	DWN	APVD
		A		RELEASED PER EC 0S12-0488-04	10JAN05	MY	SB
		B		REVISED PER EC 0S11-0007-05	14FEB05	MY	SB

- NOTES:
- MATERIAL:
 HOUSING AND EJECTOR:
 HIGH TEMPERATURE NYLON
 CONTACT:
 PHOSPHOR BRONZE
 - FINISH:
 CONTACT AREA:
 0.00076[.000030] MIN THICK GOLD
 0.00381[.000150] MIN THICK NICKEL
 SOLDER TAIL:
 0.00381[.000150] MIN THICK MATTE TIN OVER
 0.00064[.000025] MIN THICK NICKEL
 - MODULE BOARD PADS:
 FOR OPTIMUM PERFORMANCE PADS SHOULD BE SMOOTH AND FLAT
 PADS TO BE PLATED WITH:
 0.00102[.000040] MIN THICK GOLD OVER
 0.00127[.000050] MIN THICK NICKEL



SECTION Y-Y
 SCALE 5:1

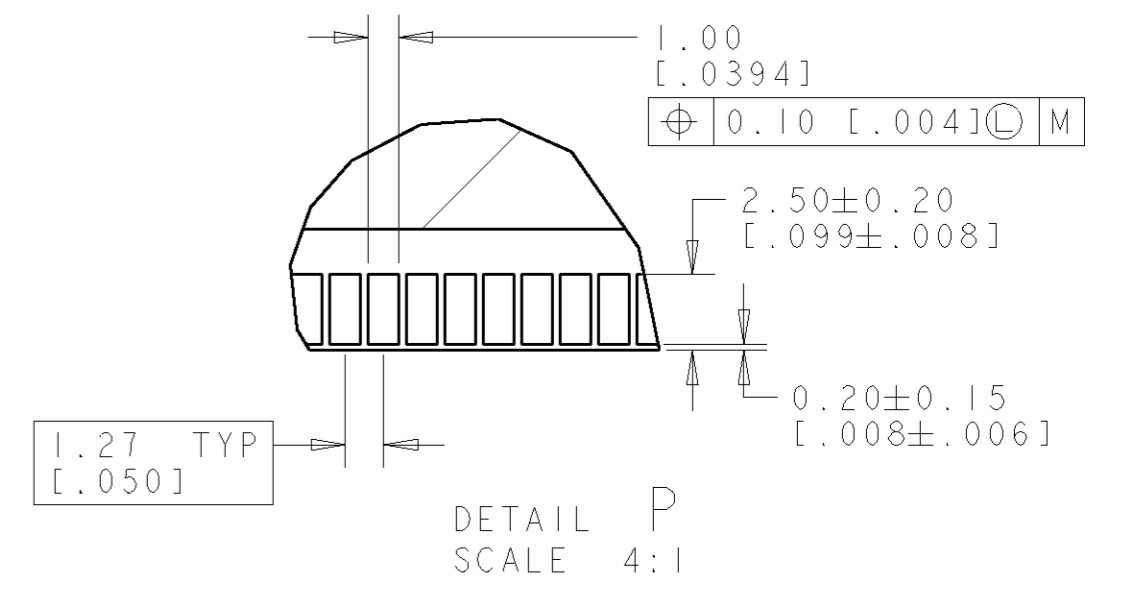
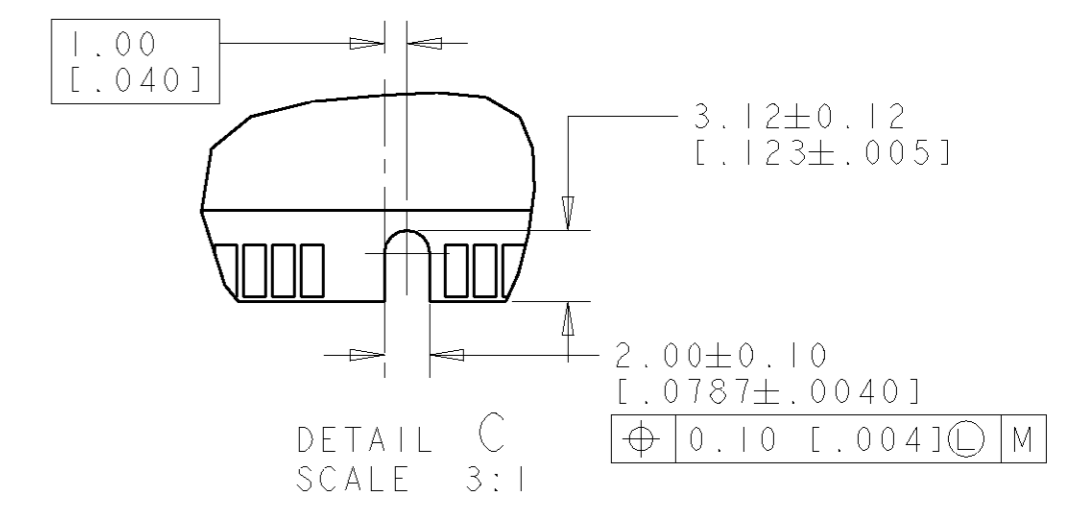
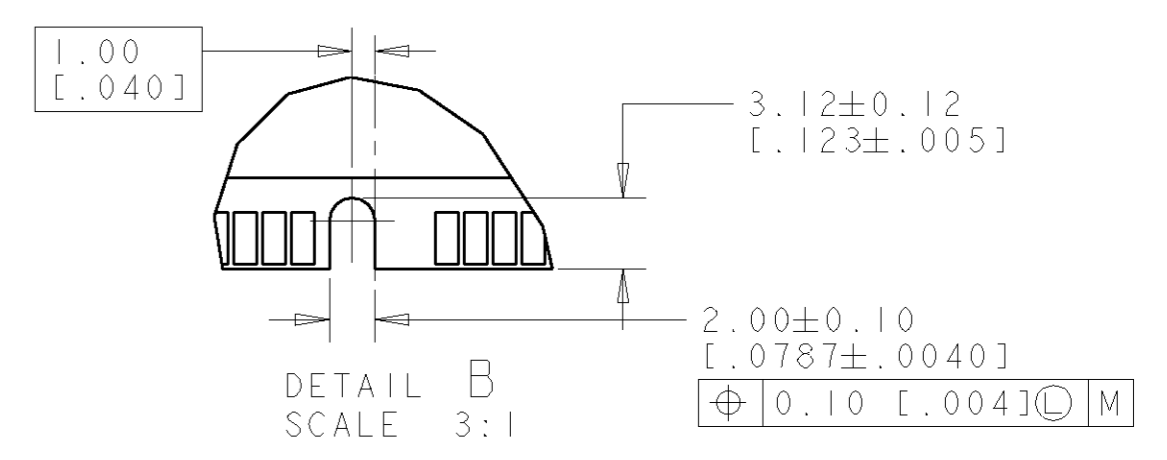
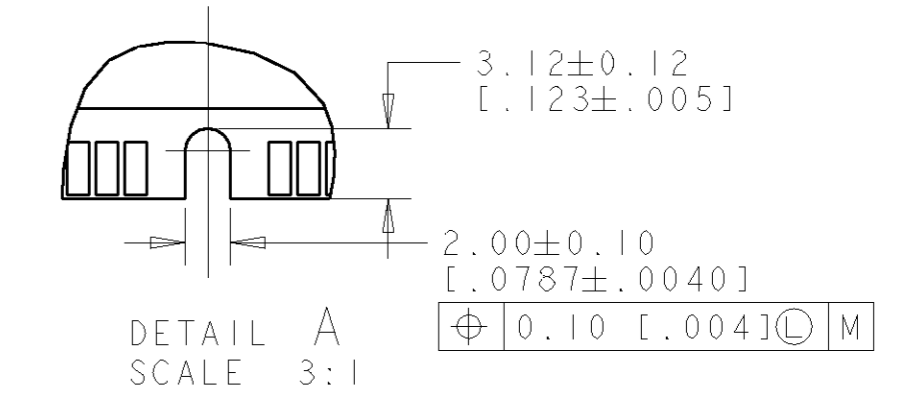
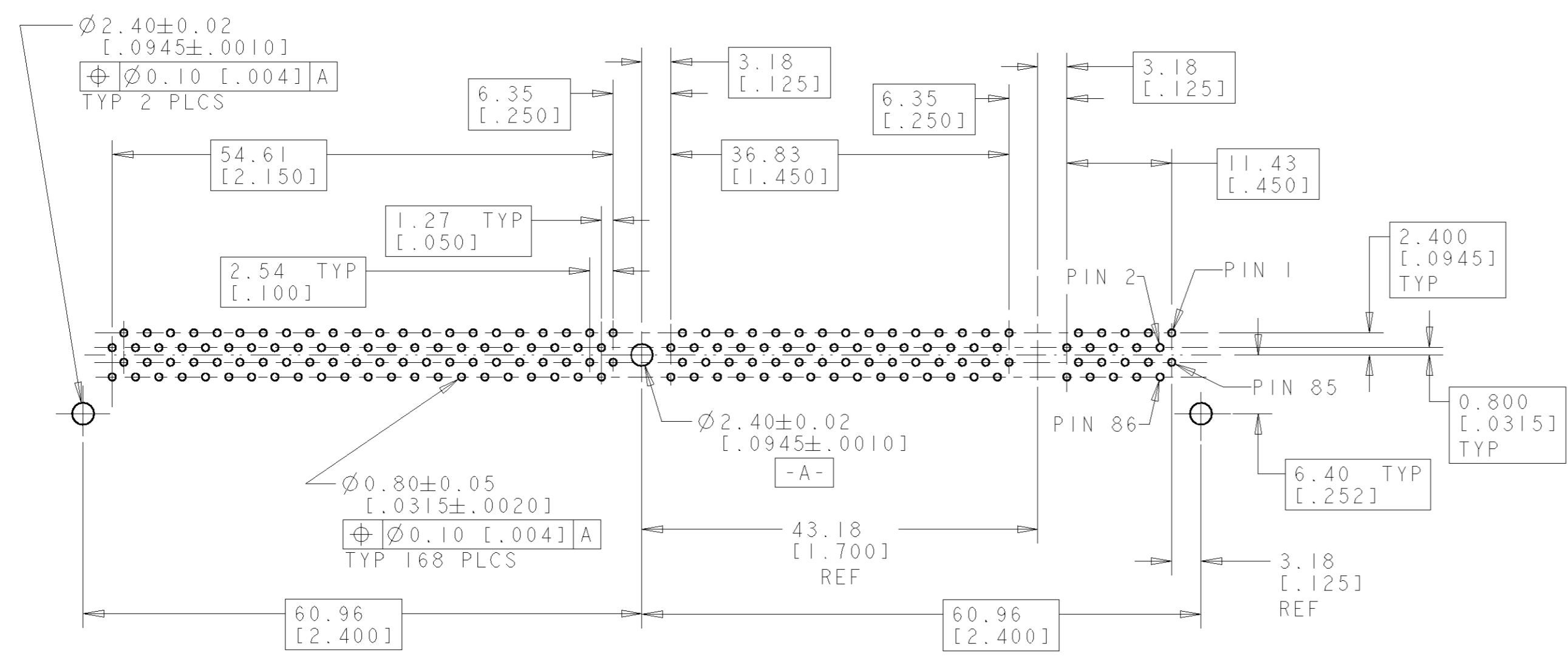
DETAIL C	DETAIL A	NON-BUFFERED DRAM, 3.3 VOLT	5390170-6
FUNCTION KEY #1	VOLTAGE KEY #2	PART DESCRIPTION	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		DWN M. YEOMANS 10JAN05 CHK M. YEOMANS 10JAN05 APVD S. BURKHOLDER 10JAN05	tyco Electronics Tyco Electronics Harrisburg, PA 17105-3608
DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.13[.005] 3 PLC ± 4 PLC ± ANGLES ± FINISH	NAME PRODUCT SPEC APPLICATION SPEC WEIGHT	NAME SIZE CAGE CODE DRAWING NO RESTRICTED TO
MATERIAL	FINISH	WEIGHT CUSTOMER DRAWING	A2 00779 G-5390170 SCALE 2:1 SHEET 1 OF 3 REV B

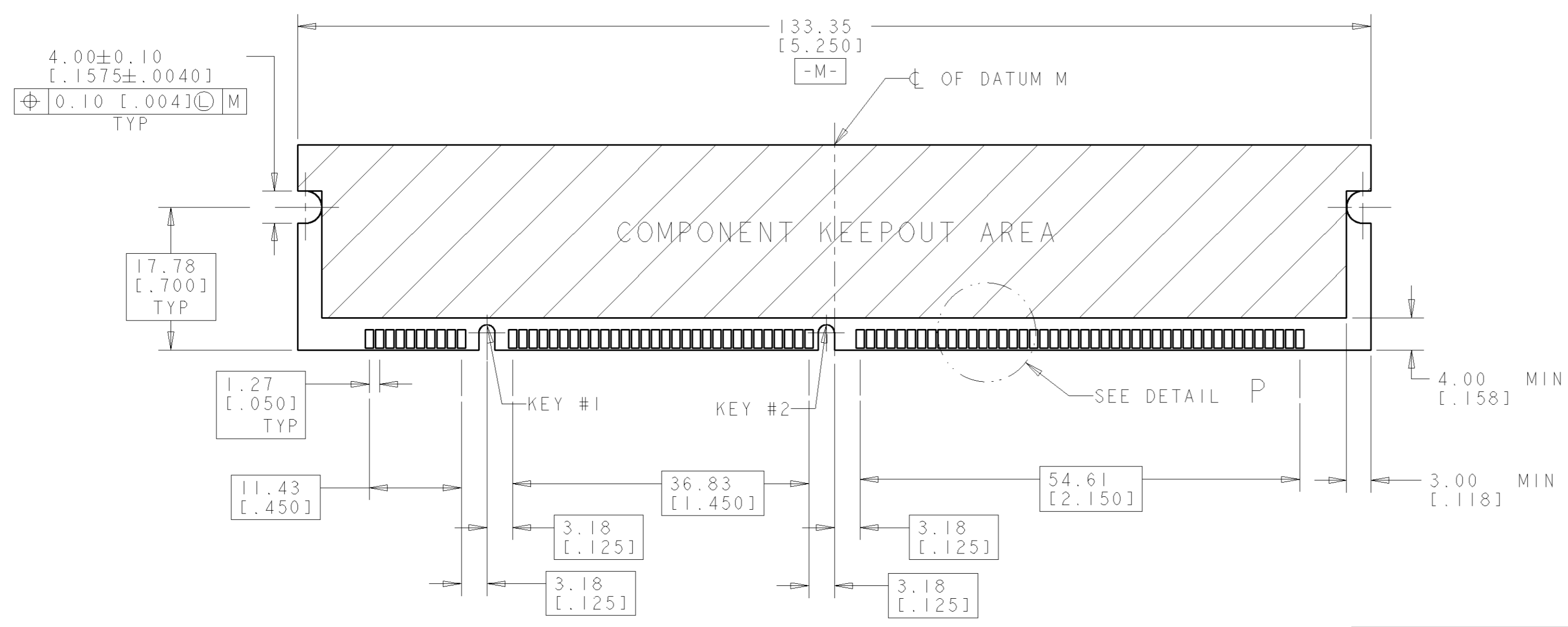
5390170

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LOC	DIST	REVISIONS					
GP	0	P	LTR	DESCRIPTION	DATE	DWN	APVD
		-		SEE SHEET 1			



RECOMMENDED CIRCUIT BOARD HOLE LAYOUT



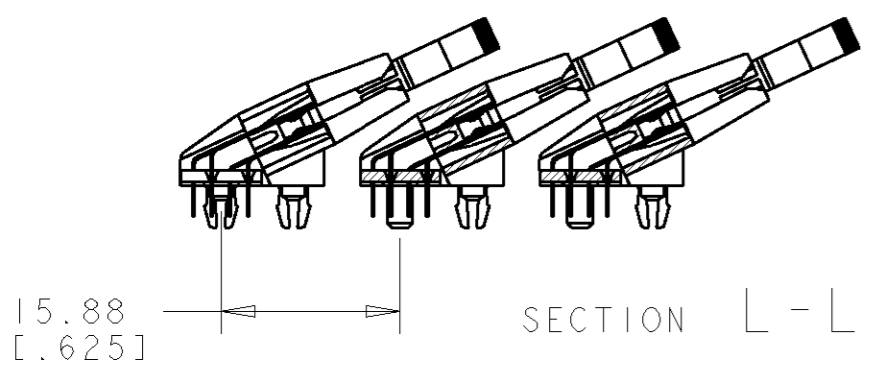
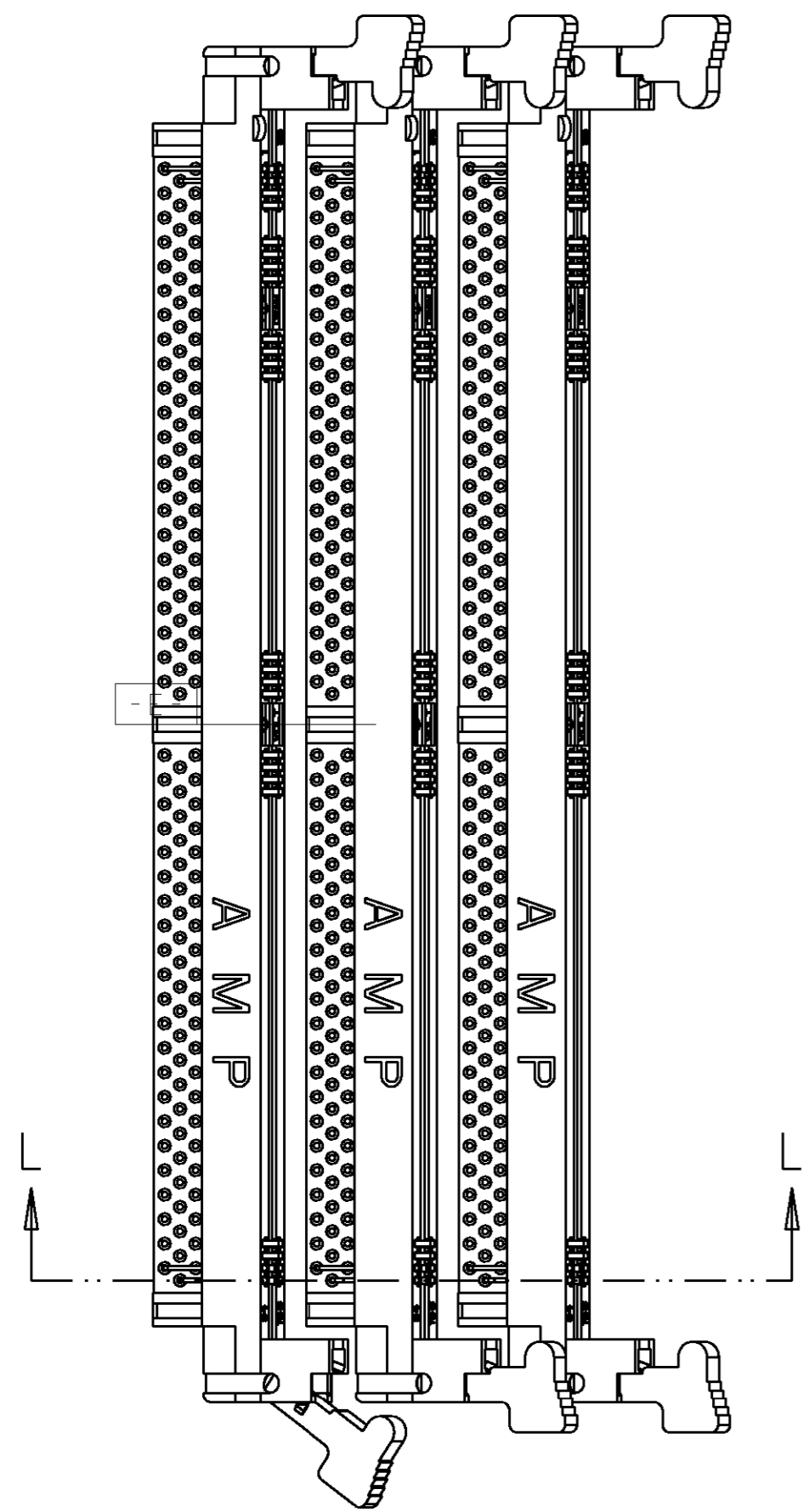
RECOMMENDED MODULE LAYOUT

SEE JEDEC SPEC. MO-161 FOR COMPLETE MODULE DETAILS
 1.27 ± 0.10 [0.050 ± 0.004] THICK ACROSS CONTACT PADS

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DIMENSIONS: mm [INCHES]		CHK M. YEOMANS 10JAN05	NAME SOCKET ASSEMBLY, 168 POSITION, CENTER PLASTIC POST 2.60 [0.103] SOLDERTAIL, LOW PROFILE DIMM 2 P	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.13 [0.005] 3 PLC ± 4 PLC ± ANGLES ± FINISH		APVD S. BURKHOLDER 10JAN05	SIZE A2	
MATERIAL		PRODUCT SPEC APPLICATION SPEC WEIGHT	DRAWING NO. 00779	
		CUSTOMER DRAWING	RESTRICTED TO SCALE 1:1 SHEET 2 OF 3 REV B	

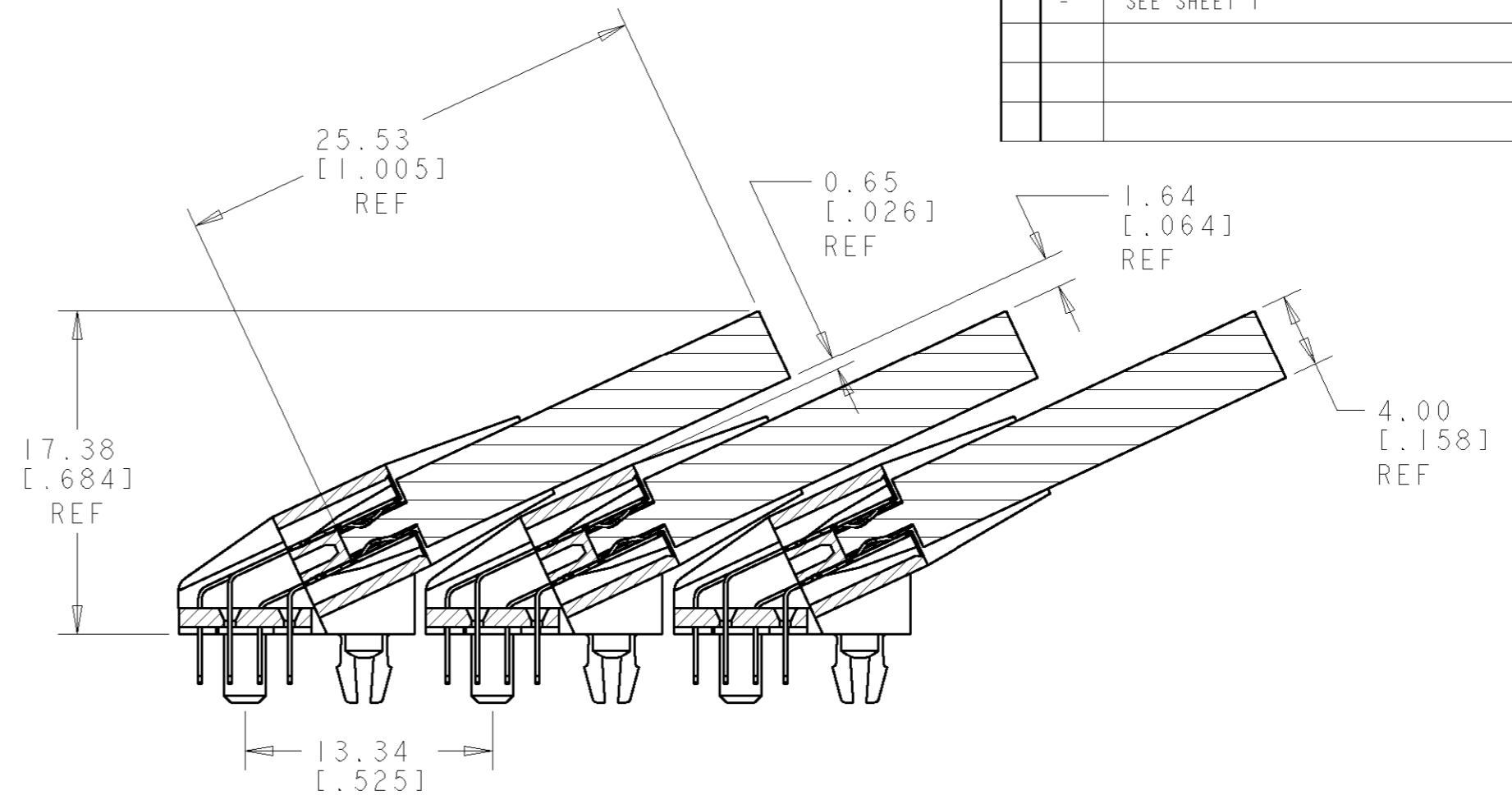
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LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
GP	0	SEE SHEET 1	-	-	-



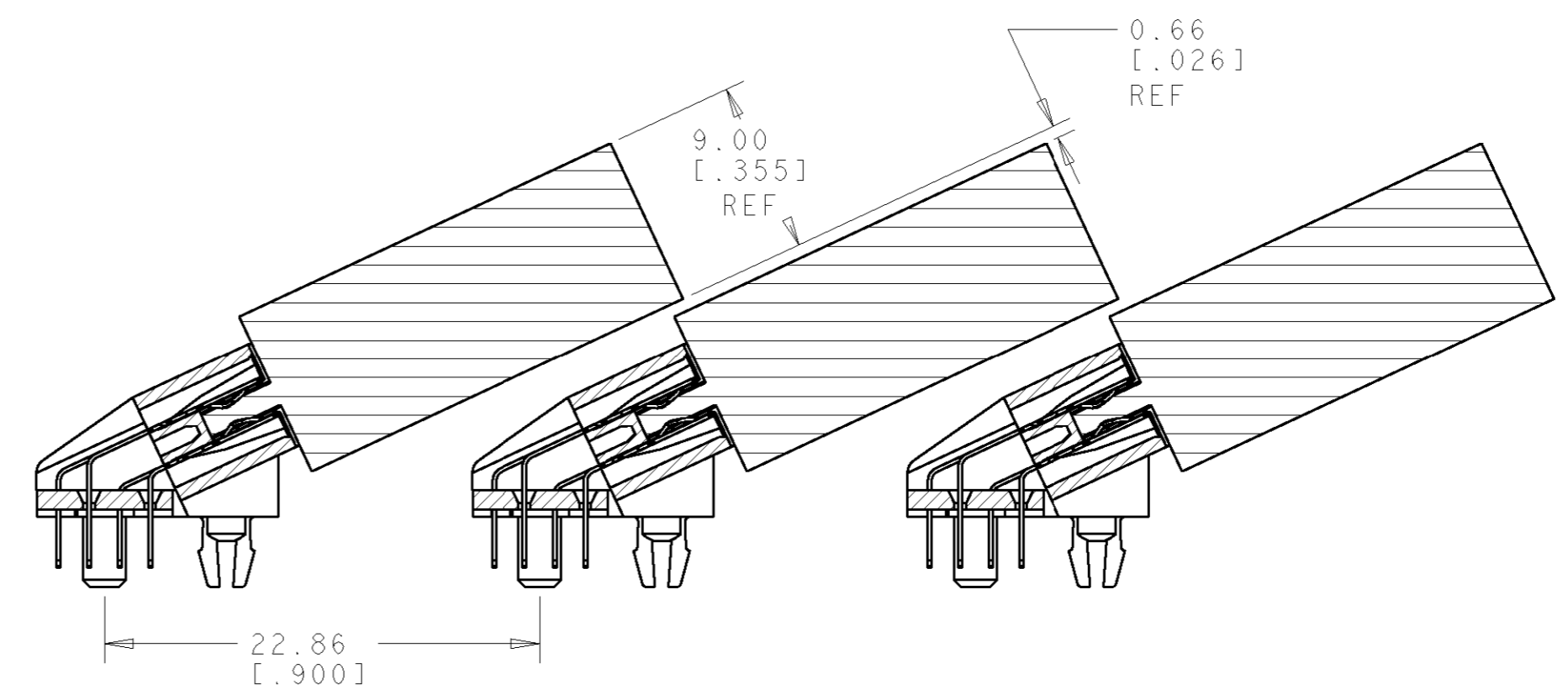
MINIMUM REPAIRABLE SOCKET TO SOCKET SPACING

WITH THE MODULES REMOVED, SOCKETS ON 15.88 [0.625] OR GREATER SPACING CAN BE INDIVIDUALLY UNSOLDERED FROM THE BOARD AND REMOVED IF NECESSARY.



MINIMUM SOCKET TO SOCKET SPACING

WITH A 4.00 [0.158] WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 13.34 [0.525] WILL LEAVE APPROXIMATELY 0.65 [0.026] OF CLEARANCE BETWEEN THE MODULE AND THE NEXT SOCKET BODY. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.



POSSIBLE SOCKET TO SOCKET SPACING FOR 9MM MODULE

WITH A 9.00 [0.355] WIDE MODULE BOARD, A SOCKET TO SOCKET SPACING OF 22.86 [0.900] WILL LEAVE APPROXIMATELY 0.66 [0.026] CLEARANCE BETWEEN THE ADJACENT MODULES. THIS SPACING MAY OR MAY NOT BE SUITABLE DEPENDING ON YOUR MINIMUM GAP REQUIREMENTS.

<small>THIS DRAWING IS A CONTROLLED DOCUMENT FOR TYCO ELECTRONICS CORPORATION. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.</small>		DWN M. YEOMANS 10JAN05 CHK M. YEOMANS 10JAN05 APVD S. BURKHOLDER 10JAN05	tyco Tyco Electronics Harrisburg, PA 17105-3608
DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.131.005 3 PLC ± 4 PLC ± ANGLES ± FINISH	NAME SOCKET ASSEMBLY, 168 POSITION, CENTER PLASTIC POST 2.60 [0.103] SOLDER TAIL, LOW PROFILE DIMM 2 P PRODUCT SPEC - APPLICATION SPEC - WEIGHT -	SIZE A2 CAGE CODE 00779 DRAWING NO. 5390170 RESTRICTED TO -
MATERIAL		CUSTOMER DRAWING	SCALE 2:1 SHEET 3 OF 3 REV B

5390170